

- 1. General specification 基本说明
 - **1.1** Scope 范围 This specification covers the requirements for single key switches which have no keytop (TACT SWITCHES:MECHANICAL CONTACT). 此规范含盖单推柄和无推柄的轻触开关要求。
 - 1.2 Operating Temperature Range 使用温度范围

-55 to 125 ℃(normal humidity, normal press).正常湿度,标准压力

1.3 Storage Temperature Rang 保存温度范围

-25 to 85 °C(normal humidity, normal press).

1.4 Test Conditions 测试条件

Tests and measurements shall be made in the following standard clnditions unless otherwise specified:

测试和计量按下列标准条件除非特殊说明

Normal temperature (temperature 5 to 35℃) 标准温度

Normal humidity (relative humidity 45 to 85%) 正常湿气

Normal pressure (pressure860 to 1060 mbars) 标准压力

In case any question arises from the judgement made, tests shall be conducted in the following conditions:

Temperature (20±2℃) 温度

Relative humidity (65±5%) 相对湿度

Pressure (860 to 1060 mbars) 压力

- 2. APPEARNCE, STYLE, AND DIMENSIONS 外形, 类型和尺寸
 - **2.1** Appearance 外形

There shall be no defects that affect the serviceability of the product 外形必须无缺陷才不影响产品适用性

2.2 Style and Dimensions 类型和尺寸

Shall conform to the assembly drawings. 符合装配图

3. TYPE OF ACTUATION 动作类型

Tactile feedback 轻触返回

4. CONTACT ARRANGEMENT <u>1</u> poles <u>1</u> throws 接触形式 1接点 1 回路

(Details of contact arrangement are given in the assembly drawings).

细接点形式在装配图中

5. MAXOMUM RATINGS DC <u>12</u> V <u>50</u> mA 最大额定值

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6.2Mechanical 机械特性

Item 项目				Requirements 规 格									
6.2.1.	Placing	the s	witch s	uch that	the d	irection	of switc						
Actuating Force	operati	on is v	ertical a										
动作力	load ap	oplied to	the cen	nd									
	require	d for t	the sten	n to co	me to	a stop	shall b	e 160±30gf					
	measu	red.											
	开关的表	动作方向	为垂直放	置开关向	推柄中心	逐渐增加	负荷直到护	推					
	柄停止时	寸所测量的	的最大负荷	र्न									
6.2.2.	Place th	he switch	n such th	at the dir	ection o	f switch of	peration	is					
Travel	vertical	and ther	apply a	static loa	d twice t	he actuat	ing force t	to					
行程	the cent	ter of the	stem, the	travel dis	stance fo	r the stem	to come t	to 0.45 . 0.4 m m					
	a stop s	hall be m	neasured.	0.15±0.1mm									
	开关的表	动作方向	为垂直放员	推									
	柄中心,	测量推柄	从开始到何	亭止的行和	呈距离								
6.2.3.	The sa	mple sv	witch is i	nstalled	such th	at the d	irection o	of					
Return Force	switch	operation	on is vei	tical and	d, upon	depress	ion of th	ne					
返回力	stem ir	n its cer	nter the v	10 of min									
	the ste	m to ret	urn to its	40gf min									
	开关的表	动作方向	垂直放置牙	压									
	力,推构	两回到自 _日	由位置时所	斤测量到的	力								
6.2.4.	Placing	g the s	witch su	uch that	the d	irection	of switc	ch .					
Stop	operati	on is v	ertical,	a static	load o	f <u>3</u> kgt	shall b	There shall be no sign of					
Strength	applied	d in the	direction	of damage mechanically and									
静止强度	<u>60</u> se	conds.		electrically									
	开关的表	动作方向	为垂直放置	静 无机械的和电气的损伤迹象									
	负荷,6	0 秒时间											
6.2.5.	Placing	the s	witch s	ch .									
Stem	operati	on is ve	ertical, th	а									
Strength	pull ap	plied o	ppsite to	on O Leef									
推柄的强度	shall be	e meası	ured.					3 kgf					
	开关的表	动作方向	为垂直放	カ									
	所测量到	到的最大和	承受力										
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ZONE SYMB	DATE	APPD	CHKD	DSGD									

6.PERFORMANCE 性能

6.1 Electrical	电气
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Item 项 目	Test Condition 试验条件	Requirements 要求
6.1.1. Contact Resistance 接触电阻	Applying a static load twice the actuating force to the center of the stem, measurements shall be made with a 1 kHz small-currentcontact resistance meter. 用两倍的动作力作静负载施加于按钮的中心,并用 1 千赫小电流接触电阻仪测量	<u>100</u> mΩmax.
6.1.2. Insulation Resistance 绝缘电阻	Measurements shall be made following application of DC 100 V potintial across terminals and across terminals and frame for one minute. 在端子之间,端子与外壳之间施加 DC100V,一分种	<u>100</u> MΩmin
6.1.3. Dielectric Witstanding voltage 电气耐压	AC250V (50Hz or 60Hz) shall be applied across terminals and across terminals and frame for one minute. 在端子与端子之间,端子与外壳之间施加 AC250V(50Hz or 60Hz)	There shall be mo breakdown 没有击穿
6.1.4. Bounce 抖动	Lightly striking the center of the stem at a rate encountered in normal use (3 to 4 operations per sec), Bounce shall be tested at "ON" and "OFF" 在正常使用中(以每秒 3-4 次周期)轻轻地在手柄中心加力,在通与断瞬间测试抖动。	<u>10</u> m sec max .
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ZONE SYMB	DATE APPD CHKD DSGD	3/7

TACT	SWITCH	SPECIFICATION(轻	触	开	关	说	明	书)
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6.3 Environmental 环境

Item 项 目	 Test Condition 试验条件	Requirements 要求			
6.3.1. Resistance to Low Temperatures 耐低温	Following the test set forth below the sample shall be left in mormal temperature and humidity conditions for one hour before measurements are made: 样品按下列条件进行耐低温试验,测试前在正常温度和湿度条例上放置 1 小时 (1) Temperature: -30±2℃ 温度 (2) Time: 96 hours 时间	Item 6.1 Item 6.2.1 Item 6.2.2			
6.3.2. Heat Resistance 耐 热	(3) Water drops shall be removed 擦除水珠 Following the test set forth below the sample shall be left in normal temperature and humidity conditions for one hour before measurements are made: 样品按下列条件进行耐热试验,测试前在正常温度和湿度条件下放置 1 小时(1) Temperature:80±10℃ 温度 (2) Time: 96 hours 时间	Item 6.1 Item 6.2.1 Item 6.2.2			
6.3.3. Moisture Resistance 耐潮湿	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for one hour before measurements are made: 样品按下列条件进行耐潮湿试验,测试前在正常温度和湿度条件下放置 1小时 (1) Temperature: 60±2℃ 温度 (2) Relative humidity: 90 to 95% 相对湿度 (3) Time: 96 hours 时间 (4) Water drops shall be removed 擦除水珠	Contact resistance: 100 m ohm max 接触电阻 Insulation resistance 100 M ohm min.绝缘电阻 Item 6.1 Item 6.2.1 Item 6.2.2			
6.3.4. Temperature Cycling 温度循环	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for one hour before measurements are made. 样品按下列条件进行温度循环试验,测试前在正常温度和湿度条件下放置 1 小时 During this test, water drops shall be removed, 在试验期间,擦除水珠。	Item 6.1 Item 6.2.1 Item 6.2.2			
	APPD CHKD DSGD	TD-309XA			
ZONE SYMB	DATE APPD CHKD DSGD	4/7			

TAC	T SW	/ITCH	SPE	CIFIC	ATION	Ⅵ 轻:	触开	关说明书)
6.4 Endurance	耐久特性	生						
Item 项 目		Te	st Cond	lition 试		Requirements 要求		
6.4.1. Operating Life 动作寿命	set fou (1)DC 载 (2) Rat 动作频 ² (3)Dep (4) Cyc	th below 5V 5mA e of ope 率: 2-3 ression	resistive eration:2 次/每秒 : <u>1.5 倍</u> peration	e load . [2 to 3 op 动作力	t负 Ins 100 Act	ntact resistance: OmΩ max 接触电阻 ulation resistance: OMΩmin.绝缘电阻 tuating force: 动作力 + 15 % or -15%of initial force. 5%初始动作力 Item 6.1.3 Item 6.2.2		
6.4.2. Vibration Resistance 耐振动	Measurements shall be made following the test set forth below: 按下列条件进行抗振动试验 (1) Range of oscillation: 10 to 55 Hz 频率范围 (2) Amplitude,pk-to -pk: 1.5mm 振幅: 峰-峰 1.5mm (3) Cycle of sweep: 10-55-10Hz in one minute, approx (4) Mode of sweep: Logarithmically sweep or (5) uniform sweep. 扫描周期: 10-55-10-Hz 约一分钟内 (6) Direction of oscillation: 振动方向Three mutually perpendicular directions, including the direction of stem travel, 3 个相互垂直方向,包括推柄行程方向 (7) Duration of testing 持续时间2 hours each ,for a total of 6hours. 每方向2 小时,							Item 6.1 Item 6.2.1 Item 6.2.2
6.4.3. Impact Shock Resistance 抗冲击	共 6 小时 Measurements shall be made following the test set forth below:按下列条件进行冲击试验 (1) Acceleration: 80g 加速度 (2) Cycles of test: 3 cycles each in 6 directions, (3) for a total of 18cycles 试验次数:每个方向 3 次,6 个方向共 18 次							Item 6.1 Item 6.2.1 Item 6.2.2
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ZONE SYMB	DATE	APPD	CHKD	DSGD				5/7

7.1 Other precautions 其他注意事项

(1) Following the soldering process, do not try to clean the switch with a solvent or the like .

进行焊接过程中,不可以用溶剂或类似品清洗开关

(2) Safeguard the switch assembly against flux penetration from its topside.

防止助焊剂从开关的顶端渗入。

(3) Please have the products keep in close status and the storage time is 90 days guaranty after delivering the goods at most.

交货后保证开关处于封密状态并库存时间不超过90天以上

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7.2 SWITCH HANDLING PRECAUTION 使用开关时注意事项

1. In case an automatic flow soldering apparatus is use for soldering.

用自动焊接设备焊接时应参照如下条件

可目 PREHEAT TEMPERATURE 预热温度 PREHEAT TIME 预热制度 PREHEAT TIME 预热制间 TO SUCH AN EXTENT THAT FLUX WILL BE KEPT FLUSH WHICH COMPONENTS ARE MOUNTED.PRDPARATORY FLUX MUST NOT BE APPLIED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED.PRDPARATORY FLUX MUST NOT BE APPLIED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED.PRDPARATORY FLUX MUST NOT BE APPLIED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED AND TO THE AREA WHIERE TERMINALS ARE LOCATED. DIPPLIED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED AND TO THE AREA WHIERE TERMINALS ARE LOCATED. DIPPLIED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED AND TO THE AREA WHIERE TERMINALS ARE LOCATED. DIPPLIED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED AND TO THE AREA WHIERE TERMINALS ARE LOCATED. DIPPLIED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED AND TO THE AREA WHIERE TERMINALS ARE LOCATED. DIPPLIED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED.PRIDED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED.PRIDED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED.PRIDED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED.PRIDED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED.PRIDED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED.PRIDED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED.PRIDED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED.PRIDED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED.PRIDED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED.PRIDED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED.PRIDED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED.PRIDED TO THAT SODE OF THE MOUNTED TO THAT SODE OF THE MOUNTED TO THAT SODE OF THE MOUNTED TO THAT SOD		
TEMPERATURE	ITEM	SOLDERING CONDITIONS
PREHEAT TEMPERATURE 预热温度 PREHEAT TIME 预热制度 PREHEAT TIME 预热时间 TO SUCH AN EXTENT THAT FLUX WILL BE KEPT FLUSH WITH THE PRINTED CIRCUIT BOARD, TOP SURFACE ON WHICH COMPONENTS ARE MOUNTED.PRDPARATORY FLUX MUST NOT BE APPLIED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED AND TO THE AREA WHIERE TERMINALS ARE LOCATED. 助焊剂应涂在电路板上组装开关的印刷面上半部位,应防止助焊剂过量到电路板. SOLDERIN TEMPERATURE 焊锡温度 DURATION OF SOLDER IMMERSION 焊接时间 ALLOWABLE PREQUENCY ALLOWABLE PREQUENCY ALLOWABLE TIME AS SEC MAX ALLOWABLE TIMES MAX	项 目	焊接条件
TEMPERATURE 预热温度 ON ITS SOLDERING SIDE) (电路板周围焊锡面的温度) PREHEAT TIME 预热时间 45 SEC MAX 45 W MAX TO SUCH AN EXTENT THAT FLUX WILL BE KEPT FLUSH WITH THE PRINTED CIRCUIT BOARDS, TOP SURFACE ON WHICH COMPONENTS ARE MOUNTED.PRDPARATORY FLUX MUST NOT BE APPLIED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED AND TO THE AREA WHIERE TERMINALS ARE LOCATED. 助焊剂应涂在电路板上组装开关的印刷面上半部位,应防止助焊剂过量到电路板. SOLDERIN TEMPERATURE 焊锡温度 DURATION OF SOLDER IMMERSION 焊接时间 ALLOWABLE PREQUENCY 2 TIMES MAX 2 MAX		180°C MAX
所熱温度 PREHEAT TIME 我		(AMBIENT TEMPERATURE OF PRINTED CIRCUIT BOARD
度) PREHEAT TIME		ON ITS SOLDERING SIDE) (电路板周围焊锡面的温
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TO SUCH AN EXTENT THAT FLUX WILL BE KEPT FLUSH WITH THE PRINTED CIRCUIT BOARDS, TOP SURFACE ON WHICH COMPONENTS ARE MOUNTED.PRDPARATORY FLUX MUST NOT BE APPLIED TO THAT SODE OF PRINTED CIRCUIT BOARD ON WHICH COMPONENTS ARE MOUNTED AND TO THE AREA WHIERE TERMINALS ARE LOCATED. 助焊剂应涂在电路板上组装开关的印刷面上半部位,应防止助焊剂过量到电路板. SOLDERIN TEMPERATURE 焊锡温度 DURATION OF SOLDER IMMERSION 焊接时间 ALLOWABLE PREQUENCY TO SUCH AN EXTENT THAT FLUX WILL BE KEPT FLUSH WILL BE KEPT FLUSH WITH THAT FLUX WILL BE KEPT FLUSH WITH SOLD FLUSH WITH THAT FLUX WILL BE KEPT FLUSH WITH SOLD FLUSH ARE MOUNTED. FOR SURFACE ON WHICH COMPONENTS ARE MOUNTED.PROPARATORY FLUX WILL BE KEPT FLUSH WITH SOLD FLUX WILL BE KEPT FLUX WILL BE KEPT FLUSH WITH SOLD FLUX WILL BE KEPT FLUSH WITH SOLD FLUX WILL BE KEPT FLUX WILL BE KEPT FLUX WILL BOOK FLUX WILL BE KEPT FLUX WILL BOOK FLUX WILL BE KEPT FLUX WILL BE WILL BE WILL BE WILL BE WILL BE W	PREHEAT TIME	45 SEC MAX
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TEMPERATURE 焊锡温度 DURATION OF SOLDER IMMERSION F接时间 ALLOWABLE PREQUENCY 255℃ MAX 5 SEC MAX 5 秒 MAX 2 TIMES MAX	SOLDERIN	255°C MAY
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ALLOWABLE 2 TIMES MAX PREQUENCY 2 1/2 MAX	IMMERSION	5 秒 MAX
PREQUENCY 2 TIMES MAX	焊接时间	
PREQUENCY 2 ½ MAX	ALLOWABLE	2 TIMES MAY
允许重焊次数 2 次 WAX	PREQUENCY	
	允许重焊次数	Z (X WAX

2. Other precautions 其他注意事项

(1) FOLLOWING THE SOLDERING PROCESS, DO NOT TRY TO CLEAN THE SWITCH SOLVENT OR THE LIKE.

进行焊接工艺时不应使用不整洁的东西对开关进行清洁。

(2) SAFEGUARD THE SWITCH ASSEMBLY AGAINST FLUX PENETRA TION FROM ITS TOP SIDE. 在组装开关时应防止助焊剂从开关的上部流入到开关内部。

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